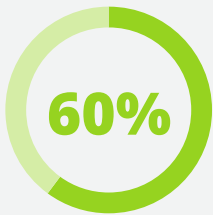




LOWER
power
consumption



BETTER
heat pumping
density

Differentiate Your Package with a Higher-Quality TEC

The requirements of cooled laser packages are evolving. Datacom optical component customers are demanding innovation and releasing new technology faster than ever. The transition from 100G to 400G in the datacenter will happen very quickly. Transceiver companies need to innovate fast - without increasing cost - to differentiate.

A Phononic TEC delivers up to 30% lower power consumption and 60% better heat pumping density.

Get a reliable, inside-the-package edge over your competitors.

Application-Specific Products

Do you lack in-house thermal design capability or have TECs that don't perform? Even if you've never designed with a TEC before, don't worry. We carry off-the-shelf options of all shapes and sizes, but we never push you into a standard solution that doesn't fit. Most TECs we produce are designed specifically for your application, to meet exact specifications and package parameters.

We model thoroughly so that once we move beyond design, it's done right, avoiding costly and time-intensive redesigns.



FBP009364



FBM008832



FBM009395



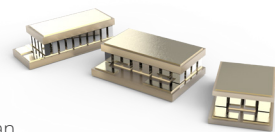
FBM009394



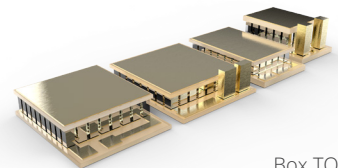
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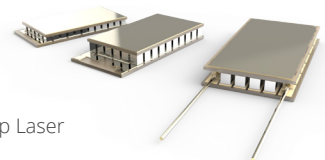
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TO Can



Box TOSA

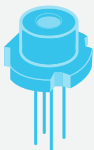


Pump Laser

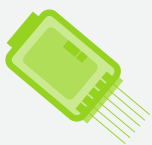




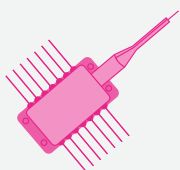
Perfect for any package type:



TO can



Box TOSA



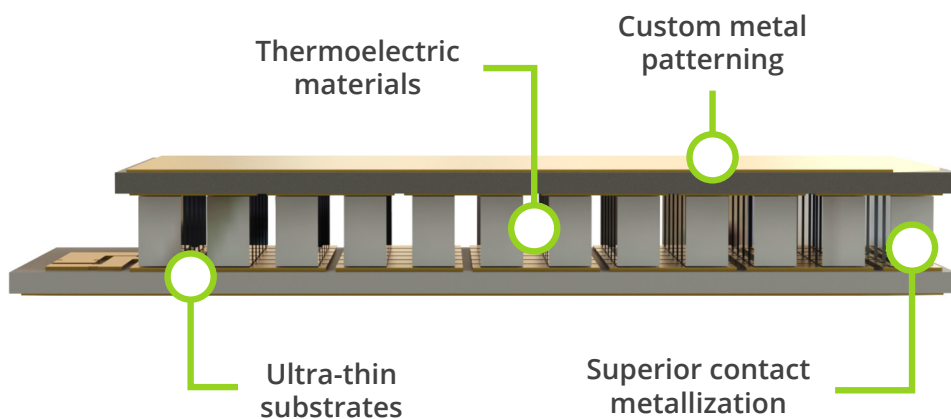
Pump lasers

Built to Be Different

Tight process control and metrology drives repeatable, unrivaled quality. Our TECs are assembled in a US-based, ISO-certified, automated manufacturing facility, not an R&D lab with an unstable manufacturing process. When you're ready, we scale very quickly from design into production, reducing your NPI timeline.

Our return rate in high-volume production is 0% (yes, zero) for a reason.

- High accuracy modeling for "First-Time Right" products, shortening design cycles and manufacturing lead times
- Expertise in high heat flux (Q/A), high efficiency and large ΔT applications
- Form factor optimized per application with sub-millimeter devices thickness and side dimensions possible
- Quick-turn design and manufacturing - don't settle for a "standard" solution
- Electrical interconnect flexibility including wires, wire-bond posts, custom metallization patterning and other custom configurations



Discover the Difference for Yourself

Visit us today at content.phononic.com/OPT/Get-Started or call us at **888.476.4202** for an expert assessment of your requirements.

Version 2003A